

ABSTRACT OF THE DISCLOSURE

2 A pin lamination method that may eliminate pits and dents formed in
3 a multi-layer printed wiring board, includes the steps of: (a) preparing steel
4 plates and coppers in a clean working room, and preparing prepgs and cores
5 in a working room; (b) laminating a first copper having a shiny surface facing
6 upward, a steel plate, and a second copper having a shiny surface facing
7 downward, thereby forming a sandwiched lamination board, with the steel
8 plate sandwiched between the first and second coppers, wherein the shiny
9 surface of each of the first and second coppers is directed toward the steel plate;
10 and (c) conveying the sandwiched lamination board to the working room, and
11 laminating the sandwiched lamination board, the prepgs, and the cores
12 serially, thereby forming a multi-layer board.